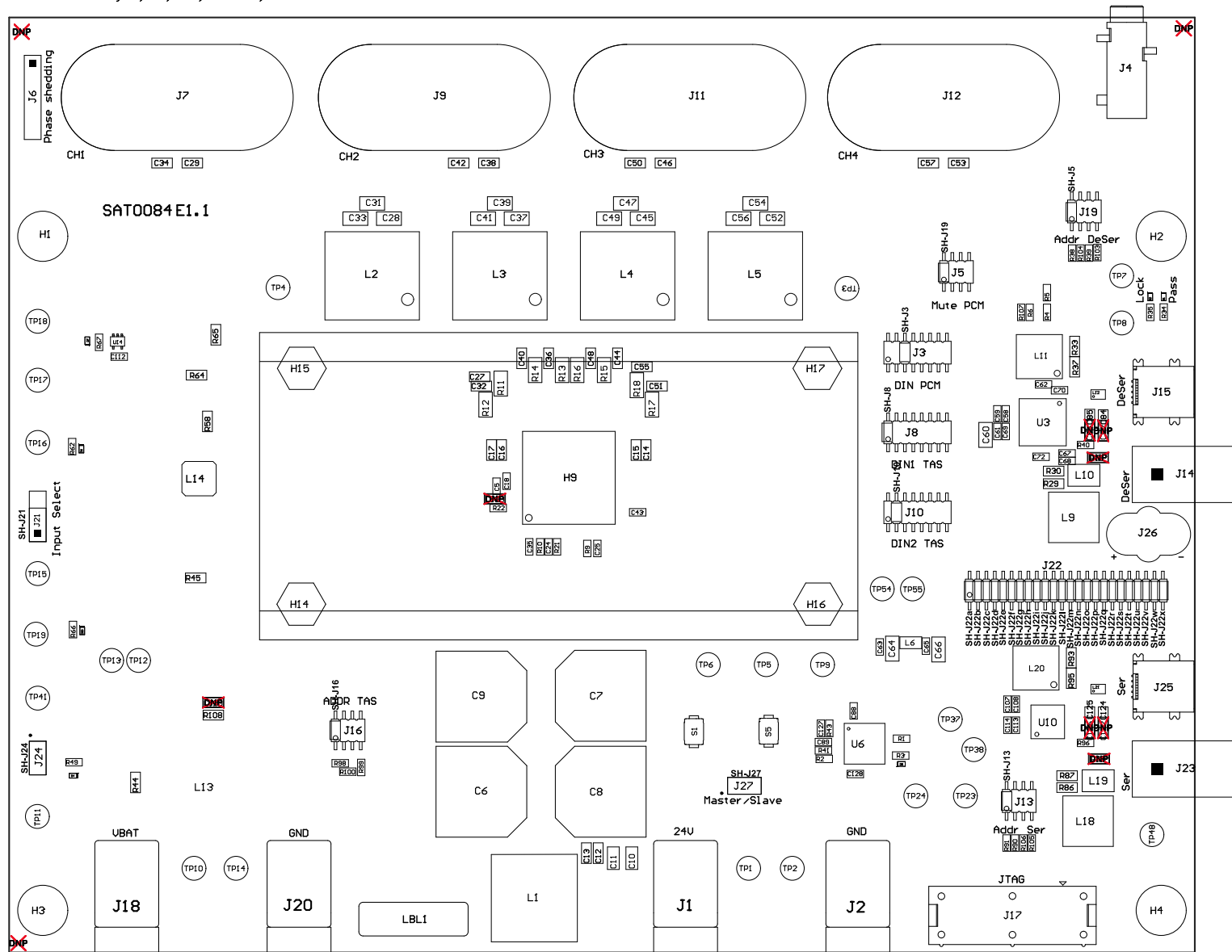
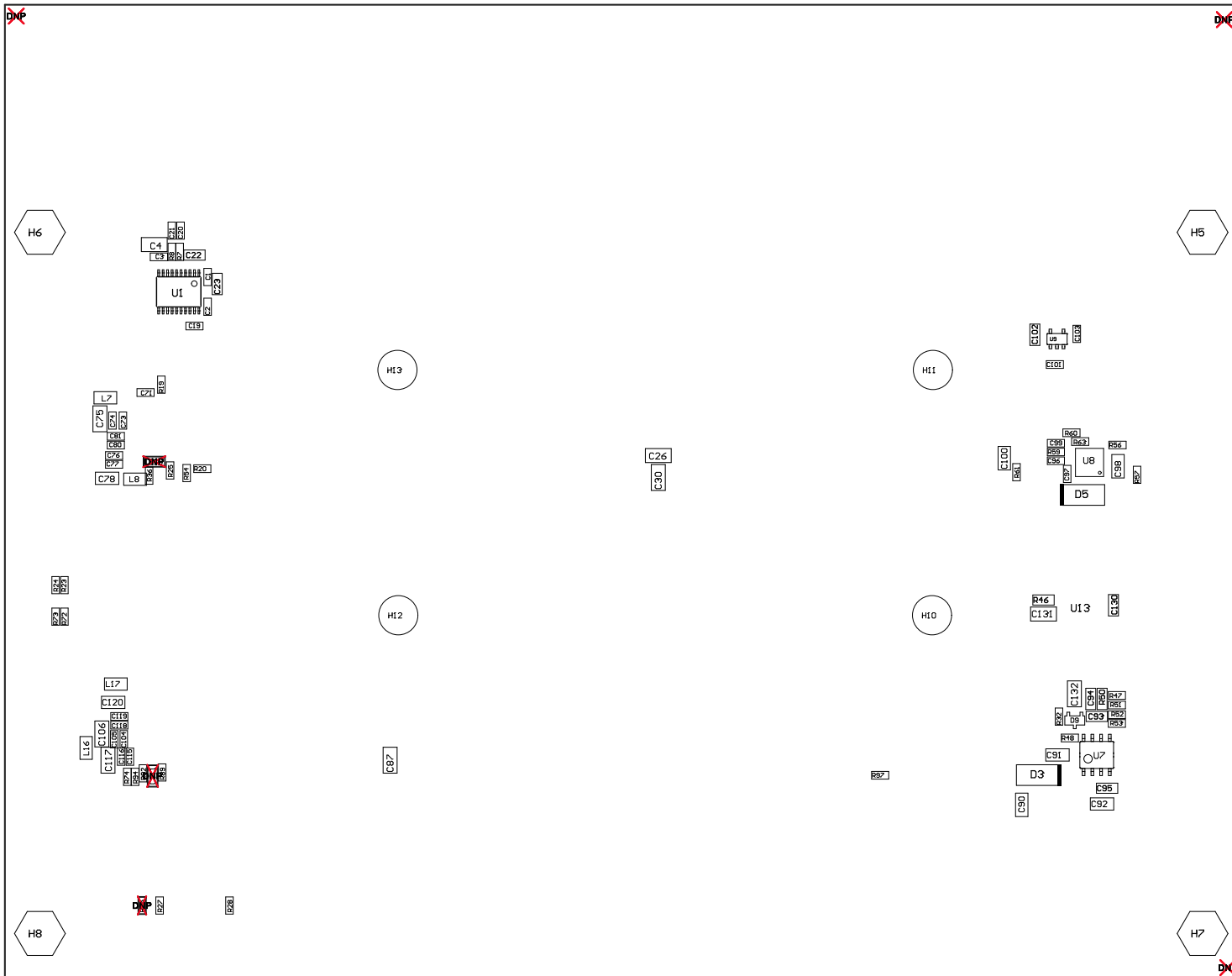


- ZZ1 ■ Installing label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- ZZ5 ■ Apply a thin layer of heatsink grease on top of U2 before installing heatsink
- ZZ6 ■ When installing J7, J8, J11, and J12, do not install the bottom-side insulator. Nuts must contact bottom copper pads.
- ZZ7 ■ When installing J1, J2, J18, and J20, solder AND bolt them



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: STP

| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM TOP SIDE | BOARD #: SAT0084 | REV: E1.1 | SUN REV: Not In VersionControl |
| IGNORE -> Top Overlay | | | |
| PLOT NAME = Top Assembly Drawing | GENERATED : 7/10/2014 11:05:53 AM | TEXAS INSTRUMENTS | |



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: STP

| | | | |
|-------------------------------------|--------------------------|-------------|--------------------------------|
| PCB VIEWED FROM BOTTOM SIDE | BOARD #: SAT0084 | REV: E1.1 | SUN REV: Not In VersionControl |
| | IGNORE -> µεlɹev0 mottob | | |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 7/10/2014 | 11:05:53 AM | TEXAS INSTRUMENTS |

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